

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1. (original): A curable polyester having at least one oxetanyl group at the molecular ends.

2. (original): The curable polyester according to claim 1, which is obtained by transesterification of a compound (A) represented by the following formula (1):



(wherein R<sup>1</sup> represents a hydrogen atom or an alkyl group having 1 to 6 carbon atoms, and R<sup>2</sup> represents an alkylene group having 1 to 6 carbon atoms), a compound (B) represented by the following formula (2):

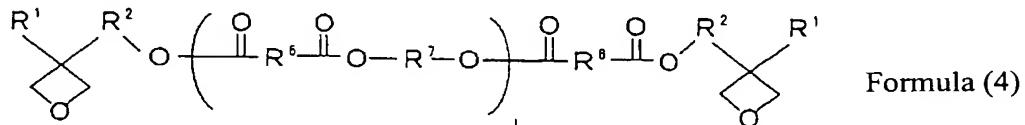


(wherein  $R^3$  represents a di- to tetra-valent organic group,  $R^4$  represents an alkyl or alkenyl group having 1 to 6 carbon atoms, and  $n$  represents an integer of 2 to 4) and a compound (C) represented by the following formula (3):



(wherein  $R^5$  represents a di- to eicosa-valent organic group, and  $m$  represents an integer of 2 to 20).

3. (currently amended): A curable polyester having an oxetanyl group at both molecular ends according to claim 1-~~or 2~~, which has a structure represented by following formula (4):



(wherein  $R^1$  represents a hydrogen atom or an alkyl group having 1 to 6 carbon atoms,  $R^2$  represents an alkylene group having 1 to 6 carbon atoms,  $R^6$  and  $R^7$  each represents a divalent organic group, and  $l$  represents an integer of 0 to 50).

4. (currently amended): A cured product obtained by curing the curable polyester of  
claim 1 any one of claims 1 to 3.

5. (original): A process for preparing a curable polyester, which comprises transesterifying a compound (A) represented by the following formula (1):



(wherein R<sup>1</sup> represents a hydrogen atom or an alkyl group having 1 to 6 carbon atoms, and R<sup>2</sup> represents an alkylene group having 1 to 6 carbon atoms), a compound (B) represented by the following formula (2):



(wherein R<sup>3</sup> represents a di- to tetra-valent organic group, R<sup>4</sup> represents an alkyl or alkenyl group having 1 to 6 carbon atoms, and n represents an integer of 2 to 4) and a compound (C) represented by the following formula (3):



(wherein R<sup>5</sup> represents a di- to eicosa-valent organic group, and m represents an integer of 2 to 20).

6. (currently amended): A resist composition comprising the curable polyester of claim 1  
~~any one of claims 1 to 3~~.

7. (original): The resist composition according to claim 6, wherein the content of the curable polyester is from 3 to 50% by weight based on the resin component of the composition.

8. (currently amended): An ink comprising the resist composition of claim 6-~~or 7~~ and a colorant.

9. (currently amended): A method for curing a resist composition, which comprises, performing pattern printing of the resist composition of claim 6-~~or 7~~ on a substrate, and curing a curable polyester having at least one oxetanyl group at the molecular ends of  
~~any one of claims 1 to 3~~ while melting with heating.

10. (currently amended): The method for curing a resist composition according to claim 9, wherein a heat melting or heat curing temperature of the curable polyester ~~of any one of claims 1 to 3~~ is from 40 to 250°C.

11. (currently amended): A heat cured product of the resist composition of claim 6-~~or~~7.

12. (currently amended): An insulation protective film comprising a cured product of the resist composition of claim 6-~~or~~7.

13. (currently amended): An interlayer insulation film comprising a cured product of the resist composition of claim 6-~~or~~7.

14. (original): A print circuit board comprising the insulation protective film of claim 12.

15. (original): A print circuit board comprising the interlayer insulation film of claim 13.

16. (currently amended): A jet printing ink composition comprising the curable polyester of claim 1 any one of claims 1 to 3.

17. (currently amended): The jet printing ink composition according to claim 16, wherein the content of the curable polyester of ~~any one of claims 1 to 3~~ is from 3 to 50% by weight based on the resin component of the composition.

18. (currently amended): The jet printing ink composition according to claim 16, which comprises an epoxy resin (B) as the resin component other than the curable polyester ~~of any one of claims 1 to 3.~~

19. (original): The jet printing ink composition according to claim 16, wherein resins in the essential component composition are dissolved in a solvent (C) or dispersed in the solvent (C).

20. (original): The jet printing ink composition according to claim 19, wherein the solvent (C) contains a solvent component having a boiling point of 180 to 260°C and a vapor pressure at 20°C of 133 Pa or less in the amount of 60% by weight or more based on the total amount of the solvent.

21. (currently amended): A cured product obtained by drying and heating the solvent (C) of jet printing ink composition of claim 19-~~or 20~~.

22. (currently amended): A method for curing a jet printing ink composition, which comprises, performing pattern printing on a substrate using the composition of ~~claim 16~~any one of claims 16 to 20 according to an ink jet system, and curing the curable polyester ~~of any one of claims 1 to 3~~ while melting with heating.

23. (currently amended): An insulation protective film comprising a cured product of the jet printing ink composition of ~~claim 16 any one of claims 16 to 20~~.

24. (currently amended): An interlayer insulation film comprising a cured product of the jet printing ink composition of ~~claim 16 any one of claims 16 to 20~~.

25. (original): A print circuit board comprising the insulation protective film of claim 23.

26. (original): A print circuit board comprising the interlayer insulation film of claim 24.